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F&K Delvotec presents Heavy Ribbon Bonding

F&K Delvotec presented its new Heavy Ribbon Bonder 66000 G5 at the SMT/Hybrid/Packaging fair 2006 in Nuremberg. This specialised version of the successful Heavy Wire Bonder is easily converted from the standard version to process aluminium ribbon for power applications.

This technology has gained popularity in the last few years for a number of power applications because it features higher current carrying power on a smaller contact area while simultaneously increasing bonding productivity. Nonetheless the bond process remains robust and reliable and the patented Bond Process Control BPC can be employed to improve process quality.



F&K Delvotec is a leading supplier of bonding equipment with a worldwide customer base. Customers are semiconductor manufacturers and companies in all areas of the microelectronics industry.

F&K Delvotec's goal is to deliver highest quality bond processes based on state of the art bonding equipment as well as service and support to the industry.

F&K Delvotec offers the widest range of wire bonders and bond test and inspection systems available in the market for the production of discrete devices, ICs, hybrid systems and sensors, as well as multi-chip modules (MCM), chip-on-board (COB) applications and MEMS. F&K Delvotec's customers are leaders in the semiconductor industry, power components, medical applications, automotive and transportation industry, photonics and laser, computer and peripherals, tele- and data-communication, industrial applications, sensor components, military and defence as well as aerospace applications.

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